

PATENT ABSTRACTS OF JAPAN

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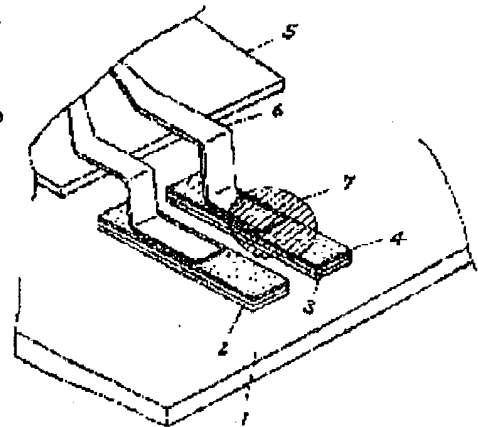
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(54) METHOD FOR SOLDERING ELECTRONIC PARTS

(57)Abstract:

PURPOSE: To provide the method for soldering an electronic parts so that a high quality soldering can be executed in a short time.

CONSTITUTION: The soldering is executed by re-flowing a cream-solder at a electrode 2 of a circuit base plate 1, or forming a soldering layer 3 by electrolytic solder-plating, etc., coating or printing a black paint 4 or a flux mixed with this black paint 4 at the upper of them, mounting the electrode 6 of the electronic part 5 at the upper of them, irradiating a laser light or laser beam at the part 7 of the surface of the above soldering layer 3 and melting the soldering layer 3.



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